

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 08250858
PUBLICATION DATE : 27-09-96

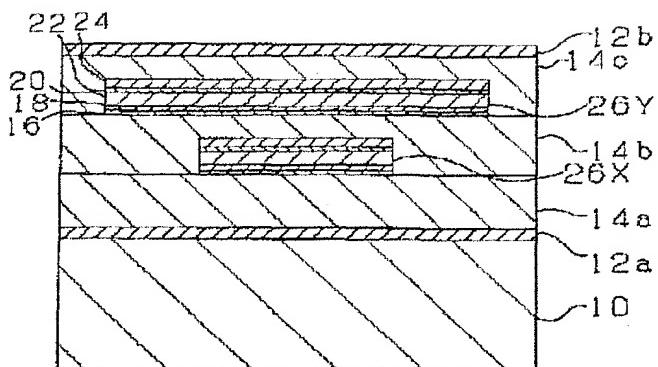
APPLICATION DATE : 07-03-95
APPLICATION NUMBER : 07077290

APPLICANT : NGK SPARK PLUG CO LTD;

INVENTOR : WAKAMATSU SUSUMU;

INT.CL. : H05K 3/46 H01P 3/08 H05K 1/09

TITLE : CIRCUIT BOARD



ABSTRACT : PURPOSE: To provide a circuit board with low loss and high signal transmission speed at high frequencies.

CONSTITUTION: On a nickel-plated layer 22 which is a magnetic material formed on a copper-plated layer 20, a gold-plated layer 24 which is a non-magnetic material is further formed. Thus when a circuit board is used at high frequencies, though inductance of the nickel-plated layer 22 increases, current flows to the overlying gold-plated layer 24 and to the underlying copper-plated layer 20 due to skin effects, while no current flows to the nickel-plated layer 22 made of the magnetic material located in between, thereby generating no transmission loss due to the nickel-plated layer 22.

COPYRIGHT: (C)1996,JPO